



Material Composition Declaration

EPC2054

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/12/2021
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	4.9 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	4.5188	92.4459	95.5811	924459
	Silicon oxide	7631-86-9	0.0164	0.3364		3364
	Silicon nitride	12033-89-5	0.0130	0.2652		2652
	Gallium nitride	25617-97-4	0.0313	0.6402		6402
	Aluminum	7429-90-5	0.0251	0.5125		5125
	Aluminum nitride	24304-00-5	0.0099	0.2026		2026
	Titanium	7440-32-6	0.0003	0.0060		60
	Titanium nitride	25583-20-4	0.0024	0.0485		485
	Copper	7440-50-8	0.0008	0.0171		171
	Tungsten	7440-33-7	0.0007	0.0136		136
	Polyimide		0.0534	1.0930	10930	
Under Bump Metal	Titanium	7440-32-6	0.0001	0.0022	0.0242	22
	Copper	7440-50-8	0.0011	0.0220		220
Solder Bump	Copper	7440-50-8	0.0108	0.2200	4.3947	2200
	Nickel	7440-02-0	0.0064	0.1313		1313
	Tin	7440-31-5	0.1941	3.9706		39706
	Silver	7440-22-4	0.0036	0.0728		728
Sum in total:			4.8881	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.